



Atty. Dkt. No. 025311-0115

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

#10  
K Cooper  
12-3-03

In re patent application of

Applicant: Yoshimasa KAWASE

Title: WAFER HEAT-TREATMENT SYSTEM AND WAFER HEAT-TREATMENT METHOD

Appl. No.: 10/066,783

Filing Date: February 6, 2002

Examiner: G. Wilson

Art Unit: 3749

**REPLY UNDER 37 C.F.R. § 1.111**

Mail Stop NON-FEE AMENDMENT  
Commissioner for Patents  
PO Box 1450  
Alexandria, Virginia 22313-1450

Sir:

This communication is responsive to the Non-Final Office Action dated April 8, 2003, concerning the above-referenced patent application.

**RECEIVED**

JUL 08 2003

TECHNOLOGY CENTER R3700